

Patent Claims

- 5 1. An arrangement for increasing the packing density on a printed circuit (1) with surface mounted electrical components (2), with the printed circuit (1) being formed by two films (3x, 3y) which are pressed against one another with a dielectric (4) arranged between them, and with at
10 least one of the mutually opposite faces (3a, 3b) of the films (3x, 3y) being fitted with surface mounted electrical components (2), characterized in that via holes (6b) are provided in the printed circuit (1) in order to connect the two films (3x, 3y), with each via hole (6b) being a direct
15 connection between the mutually opposite faces (3a, 3b) of the films (3x, 3y).
- 20 2. The arrangement as claimed in claim 1, characterized in that further surface mounted electrical components (2) are arranged on the faces (3c, 3d) of the films (3x, 3y) which are not mutually opposite.
- 25 3. The arrangement as claimed in one of the preceding claims, characterized in that a further layer of a dielectric (4) as well as a further film (3z) are applied to at least one face (3c, 3d) of the printed circuit (1).
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4. The arrangement as claimed in one of the preceding claims, characterized in that the films (3x, 3y, 3z) contain copper.
- 35 5. The arrangement as claimed in one of the preceding claims, characterized in that the printed circuit (1) has first contacts (6a) which are formed on at least one face (3c, 3d) of the printed circuit (1).

6. The arrangement as claimed in one of claims 3-5,
characterized in that via holes (6c) are formed
between the compressed films (3x, 3y) and the
5 further film (3z).
7. The arrangement as claimed in one of the preceding
claims, characterized in that the surface mounted
electrical components (2) are resistors, coils or
10 capacitors.
8. A stack having a plurality of printed circuits (1)
as claimed in one of the preceding claims arranged
one on top of the other.